

BONDFILM 8060

HIGH PERFORMANCE FILM ADHESIVES

Bondfilm 8060 is a glass fabric supported, low temperature curing, epoxy film adhesive. It is formulated for lid sealing microelectronics packages. It also offers a controlled bondline thickness and is an excellent choice for substrate attachments.

ADHESIVE PROPERTIES

Color	White
Work Life @ 25°C	24 hours
Hardness (Shore D)	90
Cure Options	2 hours @ 100°C
Service Temperature Range	-40°C to 150°C
Lap Shear Strength @ 25°C (Al to Al)	8000 psi
@ 25°C (Au to Au)	1500 psi
Glass Transition Temperature (Tg)	110°C
Weight Loss @ 300°C	1.2%
Coefficient of Thermal Expansion**	
Below Tg	104 x 10 ⁻⁶ in/in/°C
Above Tg	524 x 10 ⁻⁶ in/in/°C
Shelf Life	1 year @ -40°C 6 months @ 5°C

Adhesive properties are not intended to be used as specification limits.

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INSTRUCTIONS

Place film adhesive between surfaces to be bonded. Apply continuous pressure of 1-5 psi during cure, using weight or spring loaded clamp.

AVAILABILITY

Bondfilm 8060 epoxy film is available in sheet stock and die cut preforms. Die cut preforms are cut to customer specifications. Width and length tolerances are $\pm .005$ inch. Thickness tolerance $\pm .001$ inch.

STORAGE LIFE

Storage life of sheet stock is 10 days, when stored at room temperature. Storage life is 1 year at -40°C or colder.

TECHNICAL SERVICE CONTACT

For recommendations and help with any aspect of adhesive applications please contact the Bondline Technical Service Department (408) 830-9200, or via email: info@bondline.net or visit our website, www.bondline.net

CAUTION: For industrial use only. People with sensitive skin may have a reaction to this adhesive. Avoid skin contact. Wash all areas with soap and water immediately if contact does occur. It is important to refer to Safety Data Sheet (SDS) OSHA for more details.

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